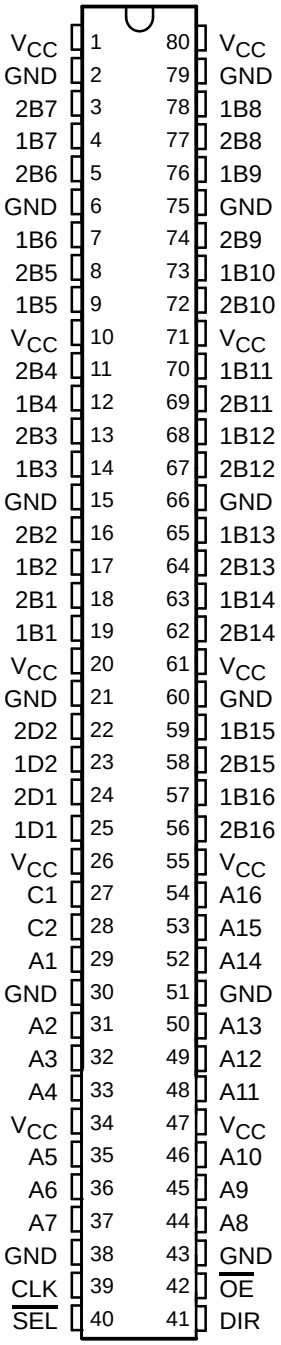
- **Member of the Texas Instruments *Widebus*™ Family**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) Sub-Micron Process**
- **A-Port Outputs Have Equivalent 50-Ω Series Resistors and B-Port Outputs Have Equivalent 20-Ω Series Resistors, So No External Resistors Are Required**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17**
- **Bus-Hold On Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Packaged in Thin Shrink Small-Outline Package**

DBB PACKAGE
(TOP VIEW)



description

The SN74ALVCHG162280 is a 16-bit to 32-bit registered bus exchanger. This device is intended for use in applications where data must be transferred from a narrow high-speed bus to a wide lower-frequency bus. It is designed specifically for low-voltage (3.3 V) V_{CC} operation.

The device provides synchronous data exchange between the two ports, A and B. Data is stored in the internal registers on the low-to-high transition of the clock (CLK) input. For data transfer in the B-to-A direction, the select ($\overline{SEL}$) input selects 1B or 2B data for the A outputs.

For data transfer in the A-to-B direction, a two-stage pipeline is provided in the 1B path, with a single storage register in the 2B path. Data flow is controlled by the active-low output-enable ($\overline{OE}$) and direction-control (DIR) input. DIR is registered to synchronize the bus direction changes with the clock.

Two mask bits are provided for both data bytes. The data (D) outputs are controlled by $\overline{OE}$.

description (continued)

The A-port N-channel output transistors are sized at 450 μm and the P-channel output transistors are sized at 700 μm. All A-port outputs have 50-Ω damping resistors. The B-port N-channel output transistors are sized at 225 μm, and the P-channel output transistors are sized at 560 μm. All B-port outputs have 20-Ω damping resistors.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The switching characteristics are based on a 25-pF (A port) and 80-pF (B and D ports) load, but are tested with the standard 50-pF load.

The SN74ALVCHG162280 is characterized for operation from 0°C to 70°C.

Function Tables

A-TO-B STORAGE ($\overline{OE}$ = L, DIR = H)

INPUTS			OUTPUTS	
$\overline{SEL}$	CLK	A	1B	2B
H	X	X	$1B_0$†	$2B_0$†
L	↑	L	L‡	L
L	↑	H	H‡	H

† Output level before indicated steady-state input conditions were established

‡ Two CLK edges are needed to propagate the data.

B-TO-A STORAGE ($\overline{OE}$ = L, DIR = L)

INPUTS				OUTPUT A
CLK	$\overline{SEL}$	1B	2B	
↑	H	X	L	L§
↑	H	X	H	H§
↑	L	L	X	L
↑	L	H	X	H

§ Two CLK edges are needed to propagate the data. The data is loaded in the first register when $\overline{SEL}$ is low and propagates to the second register when $\overline{SEL}$ is high.

C-TO-D STORAGE ($\overline{OE}$ = L)

INPUTS			OUTPUTS	
$\overline{SEL}$	CLK	C	1D	2D
H	X	X	$1D_0$†	$2D_0$†
L	↑	L	L‡	L
L	↑	H	H‡	H

† Output level before indicated steady-state input conditions were established

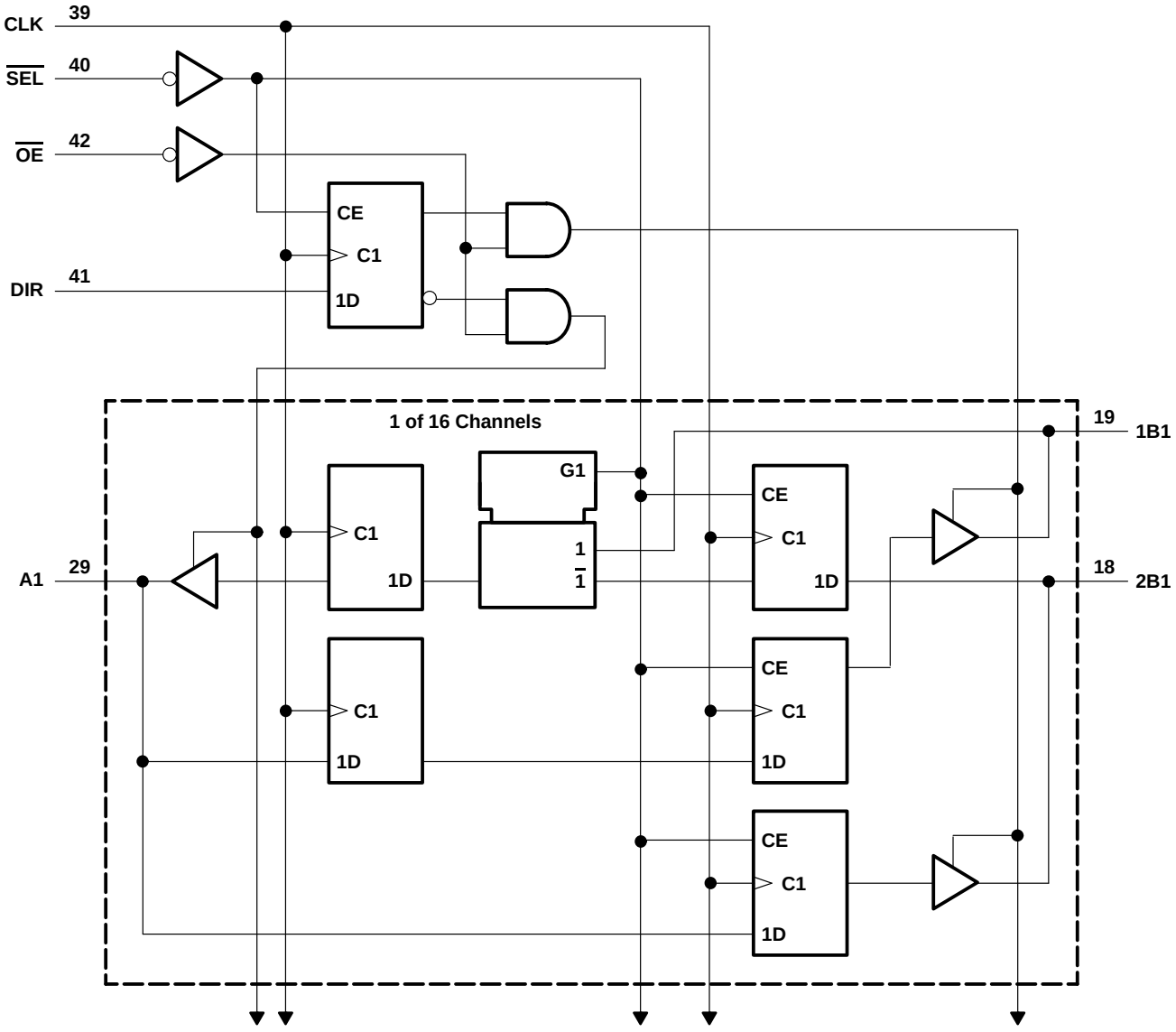
‡ Two CLK edges are needed to propagate the data.

Function Tables (Continued)

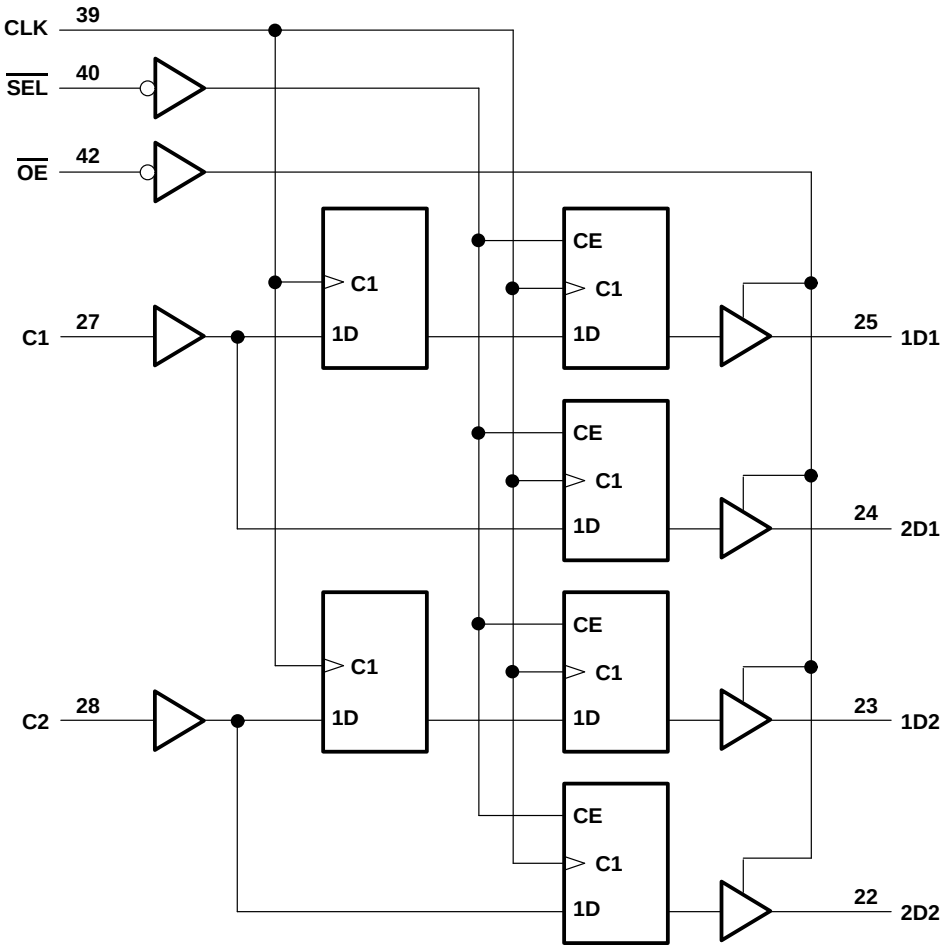
OUTPUT ENABLE

INPUTS			OUTPUTS		
CLK	$\overline{OE}$	DIR	A	1B, 2B	1D, 2D
↑	H	X	Z	Z	Z
↑	L	H	Z	Active	Active
↑	L	L	Active	Z	Active

logic diagram, A and B ports (positive logic)



logic diagram, C and D ports (positive logic)



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 4.6 V
Input voltage range, V_I (except I/O ports) (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
I/O ports (see Notes 1 and 2) . . . . . –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Notes 1 and 2) . . . . . –0.5 V to V_{CC} + 0.5 V
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Package thermal impedance, θ_{JA} (see Note 3) . . . . . 106°C/W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This value is limited to 4.6 V, maximum.
3. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 4)

				MIN	MAX	UNIT
V_{CC}	Supply voltage			3	3.6	V
V_{IH}	High-level input voltage		V_{CC} = 3 V to 3.6 V	2		V
V_{IL}	Low-level input voltage		V_{CC} = 3 V to 3.6 V		0.8	V
V_I	Input voltage			0	V_{CC}	V
V_O	Output voltage			0	V_{CC}	V
I_{OH}	High-level output current	A to B	V_{CC} = 3 V		8	mA
		B to A	V_{CC} = 3 V		6	
I_{OL}	Low-level output current	A to B	V_{CC} = 3 V		8	mA
		B to A	V_{CC} = 3 V		6	
$\Delta t/\Delta v$	Input transition rise or fall rate			0	10	ns/V
T_A	Operating free-air temperature			0	70	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP†	MAX	UNIT
V_{OH}		I_{OH} = –100 μA		3 V to 3.6 V	V_{CC}–0.2			V
	A to B	I_{OH} = –8 mA		3 V	2			
	B to A	I_{OH} = –6 mA		3 V	2			
V_{OL}		I_{OL} = 100 μA		3 V to 3.6 V			0.2	V
	A to B	I_{OL} = 8 mA		3 V			0.8	
	B to A	I_{OL} = 6 mA		3 V			0.8	
I_I		V_I = V_{CC} or GND		3.6 V			±5	μA
$I_{I(hold}$		V_I = 0.8 V		3 V	75			μA
		V_I = 2 V		3 V	–75			
		V_I = 0 to 3.6 V‡		3.6 V			±500	
I_{OZ}§		V_O = V_{CC} or GND		3.6 V			±10	μA
I_{CC}		V_I = V_{CC} or GND,	I_O = 0	3.6 V			40	μA
ΔI_{CC}		One input at V_{CC} – 0.6 V,	Other inputs at V_{CC} or GND	3 V to 3.6 V			750	μA
C_i	Control inputs	V_I = V_{CC} or GND		3.3 V		4		pF
	C port					8.5		
C_o	D port	V_O = V_{CC} or GND		3.3 V		7		pF
C_{io}	A or B ports	V_O = V_{CC} or GND		3.3 V		8.5		pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
‡ This is the bus-hold maximum dynamic current required to switch the input from one state to another.
§ For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

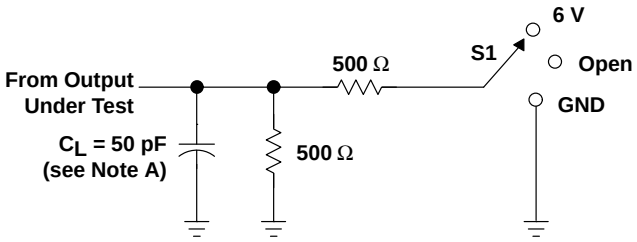
			V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	
f_{clock}	Clock frequency		0	160	MHz
t_w	Pulse duration, CLK high or low		2.3†		ns
t_{su}	Setup time, high or low	A data before CLK↑	1.4		ns
		B data before CLK↑	2		
		C data before CLK↑	1.3		
		DIR before CLK↑	2		
		$\overline{SEL}$ before CLK↑	2		
t_h	Hold time, high or low	A data after CLK↑	0.3		ns
		B data after CLK↑	0.3		
		C data after CLK↑	0.3		
		DIR after CLK↑	0.3		
		$\overline{SEL}$ after CLK↑	0.3		

† The parameter is warranted but not production tested.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 25 pF (A port), 80 pF (B and D ports) (unless otherwise noted) (see Figure 1)

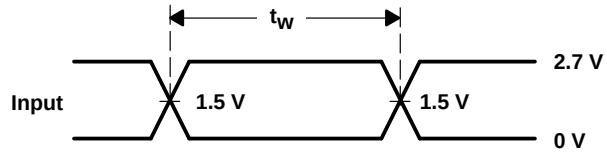
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	
f_{max}			160		MHz
t_{pd}	CLK	A	1.5	5	ns
		B	1.5	7.4	
		D	1.5	7.2	
t_{en}	CLK	A	1.5	6.2	ns
		B	1.5	9.4	
	$\overline{OE}$	A	1.5	6	
		B	1.5	9.5	
		D	1.5	7.9	
t_{dis}	CLK	A	1.5	6.4	ns
		B	1.5	7.8	
	$\overline{OE}$	A	1.5	5	
		B	1.5	7.6	
		D	1.5	6.7	

PARAMETER MEASUREMENT INFORMATION

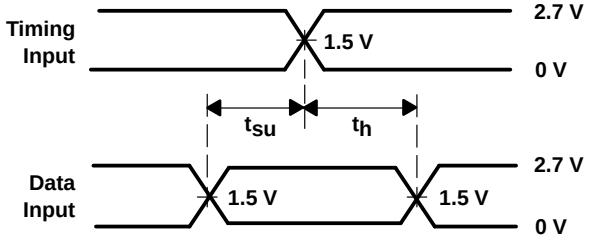


TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND

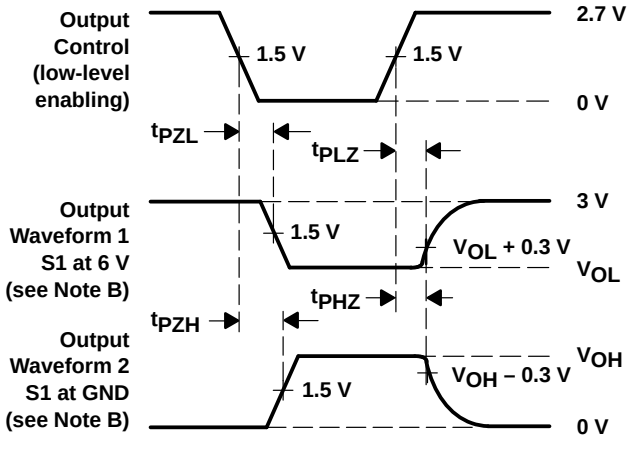
LOAD CIRCUIT



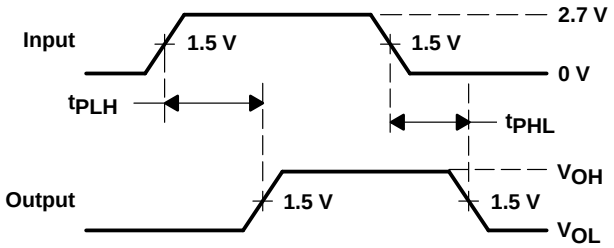
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

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